

matter from the pad. More specifically, the conventional cleaning process may only be able to suspend matter loosely adhered to the polishing pad. As such, the current cleaning process may not be able to dislodge all matter adhered to the polishing pad. Consequently, the polishing performance and efficiency of the system may degrade more quickly since additional matter may build upon the remaining matter. In addition, such a cleaning process is typically performed when the polishing system is not in use. Typically, in order to reduce downtime of the polishing system, the cleaning process is performed after a specific number (e.g., 25) of wafers has been processed. In this manner, as the polishing process continues, matter continues to accumulate upon the polishing pad and uniformity from wafer to wafer decreases. Furthermore, since the process is manual, the length and the coverage of the cleaning process may vary. As such, the performance and efficiency of the polishing system may vary, thereby reducing the process capability of the system.

Please replace pg. 8, lines 9-25, with the amended paragraph below. A "marked-up" version of each amendment is including in **Attachment A**.

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There may be several advantages to creating a method and system to remove the build-up of matter upon a polishing pad during a CMP process. For example, the fact that the system is incorporated into the CMP process may minimize interruption of the polishing process. Consequently, production throughput may be increased. In addition, the spray element included in such a system is preferably adapted to spray a fluid at a sufficient pressure such that essentially all of the matter is removed from the pad. In this manner, the pad may be cleansed completely before polishing one or more wafers. Conventional methods typically do not remove all of the matter on a pad, thereby jeopardizing the quality of the subsequent polishing process. Furthermore, the process described herein does not require manual intervention. In other words, the activation, length, and coverage of the process may be maintained in a consistent manner. In this manner, the pad may be consistently cleaned in the same manner. The variation attributed with the manual process is eliminated, thereby improving the process capability of the cleaning process and consequently the polishing process. Another advantage of the system as described herein is that it is configured to easily mount into the polishing system along with being very easy to remove. In this manner, the tool may be easily accessed for maintenance issues.
